

## PATENT ASSIGNMENT COVER SHEET

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SUBMISSION TYPE:	NEW ASSIGNMENT								
NATURE OF CONVEYANCE:	ASSIGNMENT								
CONVEYING PARTY DATA									
<table border="1"> <thead> <tr> <th>Name</th> <th>Execution Date</th> </tr> </thead> <tbody> <tr> <td>TOSHIYUKI SAWA</td> <td>09/07/2013</td> </tr> <tr> <td>SHIGEKI MORI</td> <td>09/07/2013</td> </tr> <tr> <td>JUN YAMAZAKI</td> <td>09/07/2013</td> </tr> </tbody> </table>		Name	Execution Date	TOSHIYUKI SAWA	09/07/2013	SHIGEKI MORI	09/07/2013	JUN YAMAZAKI	09/07/2013
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<table border="1"> <tr> <td>Name:</td> <td>HITACHI, LTD.</td> </tr> <tr> <td>Street Address:</td> <td>6-6, MARUNOUCHI 1-CHOME</td> </tr> <tr> <td>City:</td> <td>CHIYODA-KU, TOKYO</td> </tr> <tr> <td>State/Country:</td> <td>JAPAN</td> </tr> </table>		Name:	HITACHI, LTD.	Street Address:	6-6, MARUNOUCHI 1-CHOME	City:	CHIYODA-KU, TOKYO	State/Country:	JAPAN
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CORRESPONDENCE DATA									
<p>Fax Number: (202)628-8844          Phone: 2026242500          Email: NUnverferth@crowell.com  <i>Correspondence will be sent via US Mail when the email attempt is unsuccessful.</i>          Correspondent Name: CROWELL &amp; MORING, LLP          Address Line 1: 1001 PENNSYLVANIA AVENUE, N.W.          Address Line 4: WASHINGTON, DISTRICT OF COLUMBIA 20004</p>									
ATTORNEY DOCKET NUMBER:	056204.66299US								
NAME OF SUBMITTER:	MICHAEL H. JACOBS								
Signature:	/Michael H. Jacobs/								
Date:	02/14/2014								
Total Attachments: 1 source=66299US_Assignment#page1.tif									

**ASSIGNMENT**  
( 譲 渡 証 )

As a below named inventor, I hereby declare that:

IN CONSIDERATION of the sum of One Dollar (\$1.00) or the equivalent thereof, and other good and valuable consideration paid to me by Hitachi, Ltd.,  
a corporation organized under the laws of Japan,  
located at 6-6, Marunouchi 1-chome, Chiyoda-ku, Tokyo, Japan,  
receipt of which is hereby acknowledged I do hereby sell and assign to said Hitachi, Ltd.,  
its successors and assigns, all my right, title and interest, in and for the United States of America, in and to

**FORECAST SYSTEM AND METHOD OF ELECTRIC POWER DEMAND**

invented by me (if only one is named below) or us (if plural inventors are named below) and described in the application for United States Letters Patent therefor, executed on even date herewith, and all United States Letters Patent which may be granted therefor, and all divisions, continuations and extensions thereof, the said interest being the entire ownership of the said Letters Patent when granted,  
to be held and enjoyed by said Hitachi, Ltd.,  
its successors, assigns or other legal representatives, to the full end of term for which said Letters Patent may be granted as fully and entirely as the same would have been held and enjoyed by me or us if this assignment and sale had not been made;

And I hereby agree to sign and execute any further documents or instruments which may be necessary, lawful, and proper in the prosecution of the above-named application or in the preparation and prosecution of any continuing, continuation-in-part, substitute, divisional, renewal, reviewed or reissue applications or in any amendment, extension, or interference proceedings, or otherwise to secure the title thereto in said assignee;

And I do hereby authorize and request the Commissioner of Patents to issue said Letters Patent to said Hitachi, Ltd.,

Signed on the date(s) indicated aside our signatures:

INVENTOR(S) (発明者フルネームサイン)	Date Signed (署名日)
1) <u>Toshiyuki Sowa</u> Toshiyuki SAWA	<u>9/7/2013</u>
2) <u>Shigeki Mori</u> Shigeki MORI	<u>9/7/2013</u>
3) <u>Jun Yamazaki</u> Jun YAMAZAKI	<u>9/7/2013</u>
4) _____	_____
5) _____	_____
6) _____	_____
7) _____	_____
8) _____	_____
9) _____	_____
10) _____	_____